

GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2021/03/23	Ken Lin
A0.1			Change Durability Cycles	2022/08/09	Ken Lin

MATERIALS(材质)AND PLATING(电镀)

- * SHELL&COVER MATERIAL:SUS201 T=0.30MM
- PLATING:50u" MIN.NICKEL PLATED OVERALL
- * TERMINAL MATERIAL:
5PIN:C2680,T=0.20MM
4PIN:C5210,T=0.20MM

PLATING:GOLD FLASH PLATED ON CONTACT AREA,
100u" MIN.TIN PLATED ON SOLDER TAIL,
50u" MIN. NICKEL UNDERPLATED OVERALL.

- * HOUSING MATERIAL:LCP BLUE (PANTONE 300C)
HF(RoHS2.0), UL94V-0

ELECTRICAL PERFORMANCE(电气性能)

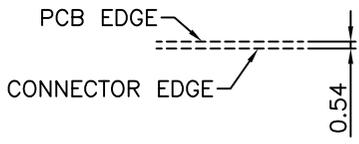
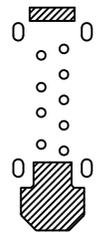
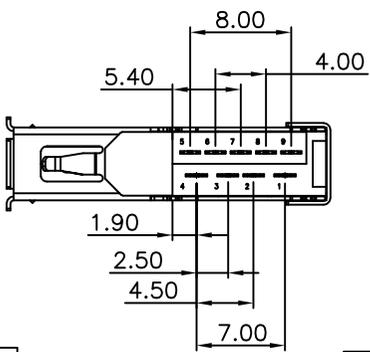
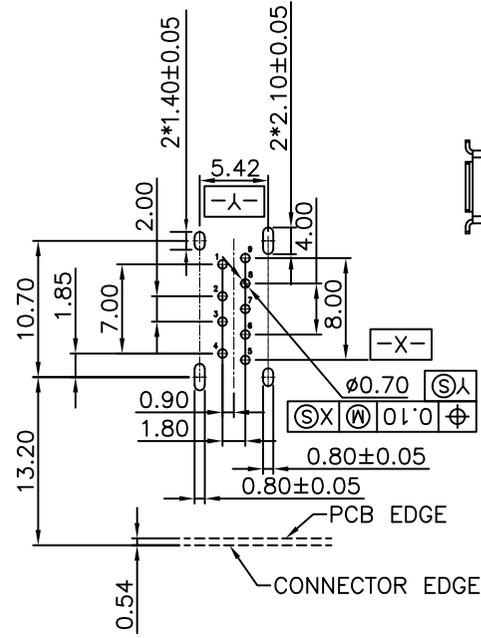
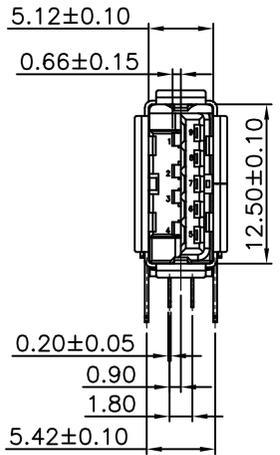
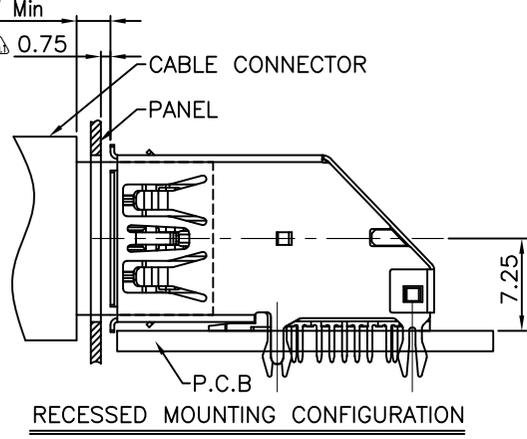
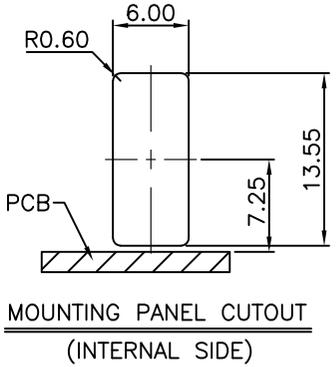
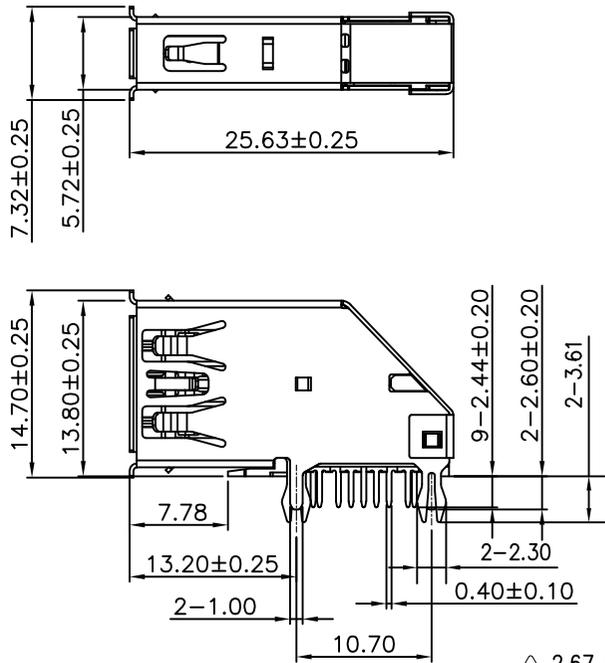
- * RATED VOLTAGE: DC 5.0V
- * RATED CURRENT: 1.8A FOR PIN1 & PIN4
0.25A FOR OTHER PINS
- * INSULATION RESISTANCE:1000 MΩ MIN.500V DC,
TEST TIME:1 SEC.MIN.
- * DIELECTIC WITHSTANDING VOLTAGE:100V AC.
TEST TIME:1 SEC.MIN.
- * CONTACT RESISTANCE: 30MΩ MAX FOR PIN1 & PIN4
50MΩ MAX FOR OTHER PINS

ENVIRONMENTAL PERFORMANCE (环境性能)

- * OPERATING TEMPERATURE :-20°C TO +85°C
- * STORAGE TEMPERATURE:-20°C TO +60°C ,
RELATIVE HUMIDITY (%):20%~70%
- * STORAGE LIFE: 6 MONTHS MAX.
- * SALT SPRAY TEST:24H FOR SOLDER TAIL ,
48H FOR OTHER AREA

MECHANICAL PERFORMANCE (机械性能)

- * DURABILITY: 5000 CYCLES
- * INSERTION FORCE: 35N MAX.
- * EXTRACTION FORCE: 10N MIN.
- * THE PEAK OF TEMPERATURE ON SOLDERING:PIP:260±5°C 60S



RECOMMENDED PCB LAYOUT
(COMPONENT SIDE)
ALL TOL IS ±0.05

PIN NO.	PIN 1	PIN 2	PIN 3	PIN 4	
SLGNL NAME	V BUS	D-	D+	GND	
REMARK	USB 2.0 CONTACT PINS				
PIN NO.	PIN 5	PIN 6	PIN 7	PIN 8	PIN 9
SLGNL NAME	STDA_SSRX-	STDA_SSRX+	GND_DRAIN	STDA_SSTX-	STDA_SSTX+
REMARK	USB 3.0 CONTACT PINS				

MATRIX PART NO:
MUSB 09 - 01 - 570

MATRIX USB Pin Number Series number

Plating
01:Gold Flash(1u" Min)
03:3u"
15:15u"
30:30u"

Matrix Electronics Co.,Ltd

TOLERANCE: X: X ±0.50 X.X ±0.40 X.XX ±0.30 X.XXX ±0.15 ANGLE: ±3	DESIGN BY : Ken Lin	DATE : 2022/08/09	PART NAME: USB3.1 Gen2 Type-A DIP 母座 反向侧插
UNIT: mm [inch]	CHECKED BY: Vicky Hsieh	DATE : 2022/08/09	PART NO.: MUSB09-01-570
SCALE:1:1 SIZE:A4	APPROVED BY1: Richard Hsieh	DATE : 2022/08/09	MOLD NO.: NA
	APPROVED BY2: Richard Hsieh	DATE : 2021/03/23	DRAW NO.: SHEET NO. 1 OF 1